

Surface Mount Type Handling Precautions 【注意事项】

■ 防潮包装

□ 当在 SMT 封装部件吸潮后,它可能在焊接时导致界面剥离。造成剥离的原因是由于 SMT 吸潮后在回流加热过程内部水气蒸发膨胀,导致支架和胶体分离。因此,防潮包装可以让包装内的水气含量达到最少。

□ 防潮包装吸水材料(硅胶干燥剂)放入到铝箔防潮袋。硅胶干燥剂吸湿的变化从蓝色到红色。

■ 保管

□ 储存条件:

打开包装之前:

LED 应保持在 30℃ 以下,相对湿度 60% 以下或在 6 个月内使用。另外,建议在密闭容器使用硅胶干燥剂。

在开封后:

本包装开包后,产品在应用到回流焊或者等条件下的工艺中时必须遵循以下两点:

a) 产品必须在 12 小时内完成焊接,且车间环境要保持在温度 $\leq 30^{\circ}\text{C}$, 相对湿度 $\leq 60\%\text{RH}$ 中。

b) 万一有未使用完的 LED 时,应存放在密闭容器并使用硅胶干燥剂防潮包,将 LED 返回到原来的防潮袋,并再次重新密封防潮包装。必须保存在相对湿度 $\leq 20\%\text{RH}$ 环境中

□ 上記已超过存储时间时,实施以下条件的烘烤处理,另外,在保管期间内如没有蓝色硅胶干燥剂,请同样进行烘烤处理,烘烤条件: $65^{\circ}\text{C} \pm 5^{\circ}\text{C}$, 超过 24 小时。且相对湿度需 $< 10\%\text{RH}$

□ 请避免在环境温度的快速转换,特别是在高湿度环境中可能发生结露。

■ 静电

□ 静电或浪涌电压可能会造成损坏发光二极管及信赖性下降。建议使用时,用防静电手腕带或防静电手套。

□ 所有设备、治具、装置类和作业区域必须正确接地。建议采取预防措施,设备安装时防止浪涌电压。

■ Moisture Proof Package

□ When moisture is absorbed into the SMT package it may vaporize and expand during soldering. There is a possibility that this can cause exfoliation of the contacts and damage the optical characteristics of the LEDs. For this reason, the moisture proof package is used to keep moisture to a minimum in the package.

□ The moisture proof package is made absorbent material (silica gel desiccants) is inserted into the aluminium moisture proof bag.

The silica gel desiccants change from blue to red if moisture had penetrated bags

■ Storage

□ Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less and $60\%\text{RH}$ or less.

The LEDs should be used within 6 months

When storing the LEDs, moisture proof packaging with absorbent material (silica gel desiccants) is recommended.

After opening the package:

After this bag is opened, devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing must be:

a) Mounted within 12 hours at factory condition of $\leq 30^{\circ}\text{C}/60\%\text{RH}$

b) If unused LEDs remain, they should be stored in the moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel desiccants). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again. Stored at $\leq 20\%\text{RH}$.

□ If the moisture absorbent material (silica gel desiccants) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following condition.

Baking treatment :more than 24 hours at 65°C and $< 10\%\text{RH}$.

□ Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.

■ Static Electricity

□ Static electricity or surge voltage damages the LEDs.

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs

□ All devices equipment and machinery must be properly grounded. It is recommended that precautions be taken against surge voltage to the equipment that mounts the LEDs

■ Soldering Conditions

	Reflow Soldering		Hand Soldering	
	Pattern①	Pattern②	Temperature Soldering time	350℃ Max 3sec.Max (one time only)
Pre-heat Pre-heat time Peak temperature Dipping time Condition	120℃~150℃ 120sec.Max 240℃ Max 10sec.Max Refer to Temperature-profile①	180℃~200℃ 120sec.Max 260℃ Max 10sec.Max Refer to Temperature-profile②		

※ Recommended soldering conditions vary according to the type of LED.

※ General solder is recommended pattern①.

※ Although the recommended soldering conditions are specified in the above table, reflow or hand soldering at the lowest possible temperature is desirable for the LEDs.

□ ALL SMT LED products are Pb-free soldering available

□ Occasionally there is an optical degradation caused by the influence of heat or ambient atmosphere during air reflow method.

□ Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. it should be confirmed beforehand whether the characteristics of the LEDs will not be damaged by repairing.

□ Reflow soldering should not be done more than two times.

□ When soldering, do not put stress on the LEDs during heating.

□ After soldering, do not warp the circuit board.

■ 焊接条件

	回流焊		手工焊接	
	模式①	模式②	温度 焊接时间	350℃ Max 3sec. Max (仅一次)
预热 预热时间 峰值温度 浸渍时间 条件	120℃~150℃ 120sec. Max 最大240℃ 10sec. Max 请参阅 温度剖面①	180℃~200℃ 120sec. Max 最大260℃ 10sec. Max 请参阅 温度剖面②		

※根据不同类型的 LED,推荐焊接条件

※一般焊料建议模式①。

※虽然上表有提示焊接条件,但回流焊时、手工焊接的峰值温度尽可能选择低的温度。

※考虑到从峰值温度到冷却温度是一个逐渐降温的过程,请避免急速冷却。

□所有的 SMT LED 产品用无铅焊锡。

□在空气回流中,受回流焊过程的热量或环境气氛的影响,它可能会导致光学变化。回流时建议使用氮气回流。

□基本不做安装后的焊接修复,当修复已经是不可避免时,请使用双头烙铁。另外,请预先确认因修复原因而可能损坏 LED 哪些特性。

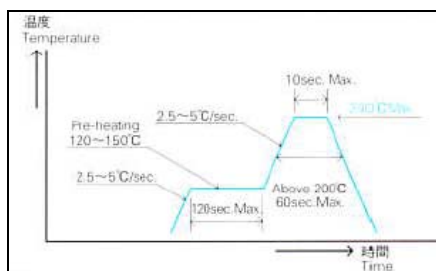
□回流焊不应该超过 2 次

□焊接时,在加热的状态下,不要对 LED 施加压力。

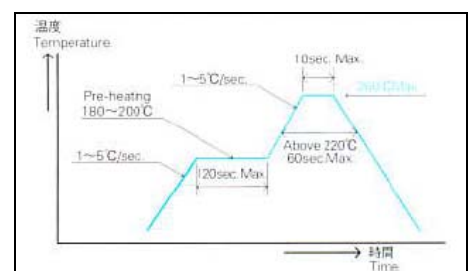
□焊接后,请不要弯曲电路板。

Temperature-Profile(Surface of Circuit Board) 电路板的表面温度资料

Pattern 模式①



Pattern 模式②



■ 热的管理

□ 终端产品的热设计是非常重要的。

做系统设计时要考虑到 LED 的发热。每个输入电功率的温度增加系数受电路板热阻力，LED 最终放置的位置及其他因素的影响。应避免剧烈的发热，操作应在规格书给的最高标准内进行。

□ 驱动电流应在考虑 LED 最高温度后再决定。

■ Thermal Management

□ Thermal design of the end product is paramount importance.

Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

□ The drive current should be decided after considering the ambient maximum temperature (T_a) of LEDs.

■ 清洗

□ 推荐用异丙醇作为溶剂清洗 LED。如用其他溶剂，应提前确认是否溶剂会溶解包装和树脂。因国际法规规定，氟利昂溶剂不应该用来清洗 LED。

□ 不要用超声波清洗 LED。如果一定要用，超声波清洗对 LED 的影响由超声波功率和组装条件决定。清洗之前，应做一个提前测试，以确保是否对 LED 有任何损害。

□ 对于某些特定的 LED 不推荐用异丙醇作为溶剂清洗。想要更多种 LED 适当的清洗方法，请参考其分别的规格书。

■ Cleaning

□ it is recommended that isopropyl alcohol be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not. Freon solvents should not be used to clean the LEDs because of worldwide regulations.

□ Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

□ it is not recommended to use isopropyl alcohol as solvent for cleaning on certain LEDs. For more information about proper cleaning methods of each LED. Please refer its respective specification sheet.

■ 眼睛的安全性

□ 2006 年由国际电工委员会 (IEC) 颁布了 IEC62471 灯和灯系统的光生物学的安全，LED 也适用这个标准范围。

□ 根据 IEC62471:2006，美卡乐的大多数 LED 可以分为豁免级或 1 类危险两种。LED 的光学特征如输出功率，光谱，配光等因素影响危险群的判定。尤其是高功率的 LED，因其发出的光中包含蓝色成分，可能会归为 2 类危险群。当直视在强电流驱动下的 LED 或者用可能会大大增加对眼睛伤害的光学仪器直视 LED 时，都应加倍小心。

■ Safety Guideline for Human Eyes

□ The international Commission (IEC) published in 2006 IEC 62471:2006 Photobiological safety of lamps and lamp systems which includes LEDs within its scope.

□ Following IEC 62471:2006, most of Multi-Color LEDs can be classified as belonging to either Exempt Group or Risk Group 1. Optical characteristics of a LED such as output power, spectrum and light distribution are factors that affect the risk group determination of the LED. Especially a high-power LED, that emits light containing blue wavelengths, may be in Risk Group 2. Great care should be taken when viewing directly the LED driven at high current or the LED with optical instruments which may greatly increase the hazard to your eyes.